

Package-type

Epson Package name; **QFP5-128PIN-S2**

JEITA Package name; **P-QFP128-1420-0.50**

Terminal plating; **Lead(Pb) Free**

Weight; **1.73 [g]*Note1**

Part	Subpart	Subpart weight [mg]	Substance name	CAS No.	Content *Note2		Application
					[mg]	[ppm]	
IC Die	IC Die	66	Silicon	7440-21-3	66	999895	Base material
			Boron	7440-42-8	0.0001	2	Dopant
			Phosphorus	7723-14-0	0.0003	5	Dopant
			Aluminum	7429-90-5	0.001	20	Metalization
			Arsenic *Note3	7440-38-2	0.0003	5	Dopant
			Fluorine *Note3	7782-41-4	0.0001	2	Dopant
			Titanium *Note3	7440-32-6	0.001	20	Metalization
			Molybdenum *Note3	7439-98-7	0.001	20	Metalization
			Tungsten *Note3	7440-33-7	0.002	30	Metalization
			Cobalt *Note3	7440-48-4	0.0001	2	Metalization
	Stress buffer coat	1.3	Polyimide	-	1.3	1000000	Stress buffer coat *Note4
Package	Die Bonding material	5.3	Silver	7440-22-4	3.6	677966	Base material
			Epoxy resin	-	1.1	207156	Adhesive
			Phenol resin	-	0.40	75330	Adhesive
			Inorganic powder	-	0.21	39548	Additive
	Lead Frame Plating	30	Tin	7440-31-5	29	979933	Solder
			Bismuth	7440-69-9	0.60	20067	Solder
	Lead Frame	318	Copper	7440-50-8	301	945003	Conductor
			Silver	7440-22-4	1.6	5028	Inner lead plating
			Others *Note5	-	16	49969	Additive
	Bonding Wire	7.4	Gold	7440-57-5	7.4	1000000	Conductor
	Mold resin	1301	Epoxy resin	-	143	109971	Base material
			Antimony trioxide	1309-64-4	10	7992	Flame retardant
			Halogenated compound(Brominations epoxy)	-	10	7992	Flame retardant
			Silica	60676-86-0/-	981	753583	Filler
Carbon black			1333-86-4	13	9990	Coloring agent	
Hardening chemical(ex:Phenol resin)			-	143	109971	Base material	
			Organic phosphorous compound	-	0.65	500	Hardening accelerator

Regarding the information of chemical substances

*Note1 The weight might be somewhat different depending on an individual built-in IC-chip specification like the size etc.

*Note2 Content data are estimated values based on supplier information and intended levels of content in product.

Actual measurements may vary from these values somewhat.

*Note3 Use or not-use of these substances depends on individual built-in IC-chip specification.

*Note4 The stress buffer coat may not be used depending on the individual model.

*Note5 The nickel, zinc, tin, silicon, iron, and the zinc oxide are included for the Cu type. And the carbon, silicon, and manganese are included for 42alloy type.